

<b>L Number</b>	<b>Hits</b>	<b>Search Text</b>	<b>DB</b>	<b>Time stamp</b>
<b>1</b>	<b>57549</b>	<b>Kondo.inv.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/09/30 13:14</b>
<b>2</b>	<b>4</b>	<b>Kondo .inv. and thermal near expansion and mounting near apparatus</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/09/30 13:15</b>
<b>3</b>	<b>36</b>	<b>IIZAKA near ATSUSHI .inv.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/09/30 13:17</b>
<b>4</b>	<b>0</b>	<b>IIZAKA near ATSUSHI .inv. and mouting near apparatus</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/09/30 13:17</b>
<b>-</b>	<b>2</b>	<b>5199855.pn.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/09/27 10:59</b>
<b>-</b>	<b>16</b>	<b>mounting adj system and frame and driver and positioning near device and image adj taking</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/09/26 07:32</b>
<b>-</b>	<b>5</b>	<b>mounting adj system and frame and driver and image adj taking and thermal adj expansion</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/09/30 13:14</b>
<b>-</b>	<b>0</b>	<b>component adj mounting near apparatus and frame and driver and thermal adj expansion near system</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/09/26 07:11</b>
<b>-</b>	<b>2</b>	<b>component adj mounting and frame and driver and thermal adj expansion near system</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/09/26 07:11</b>
<b>-</b>	<b>0</b>	<b>component near apparatus and frame and driver and thermal adj expansion near system</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/09/26 07:12</b>

-	2	c mponent near mounting and frame and driver and thermal adj expansion near system	USPAT; US-PGPUB; EP ; JPO; DERWENT; IBM_TDB	2003/09/26 07:12
-	2	component near mounting and frame and thermal adj expansion near system	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 07:12
-	3	component near mounting and thermal adj expansion near system	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 07:12
-	947	component near mounting and thermal adj expansion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 07:13
-	0	component near mounting and thermal adj expansion and image adj taken near device	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 07:13
-	10	component near mounting and thermal adj expansion and image adj taking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 07:15
-	36	29/740.ccls. and thermal near expansion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 07:16
-	554	318/600.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 07:32
-	2	6519835.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/27 11:12
-	14241172	JP 05241660.pn.	USPAT; US-PGPUB; EP ; JPO; DERWENT; IBM_TDB	2003/09/29 15:07

-	3	thermal adj expansion near ballscrew and mounting	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 15:15
-	49	thermal adj expansion near mounting and apparatus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 15:19
-	2	thermal adj expansion near mounting and apparatus and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 15:19
-	47	thermal adj expansion and mounting near apparatus and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 15:20
-	7	("4222036"   "5383270"   "5768759"   "5992013"   "6101709"   "6195454"   "6216341").PN.	USPAT	2003/09/29 15:25
-	1	"4747198".PN.	USPAT	2003/09/29 15:27